

IN THE ABSTRACT

Please replace the paragraph beginning at page 12, line 1 with the following:

ABSTRACT OF THE DISCLOSURE

A digital micro-mirror device (DMD) package is disclosed. A semiconductor chip is attached to an upper surface of a base substrate with a metallic adhesive. A metallic layer made of metal having a low melting point is formed on the back surface of the semiconductor chip. The metallic layer enables the metallic adhesive to be firmly attached to the semiconductor chip. One or more mirrors are mounted on substantially the center of the active surface of the semiconductor chip.